--14. A side-emission type semiconductor light-emitting device according to claim 5, wherein said LED chip has a bonding wire extending from a top surface, and said concave portion is formed directly above said LED chip.

15. A side-emission type semiconductor light-emitting device according to claim 6, wherein said LED chip has a bonding wire extending from a top surface, and said concave portion is formed directly above said LED chip.

16. A side-emission type semiconductor light-emitting device according to claim 12, wherein a center of said application area is deviated from a center of said substrate to said opposite direction.--

## REMARKS

The amendment herein to the claims is made to delete the multiple dependency of claims 7 and 13. New claim 14 has been added and incorporates the subject matter set forth in claim 7, except that claim 14 depends from claim 5. New claim 15 has been added and incorporates the subject matter set forth in claim 7, except that claim 15 depends from claim 6. New claim 16 has been added and incorporates the subject matter set forth in claim 13, except that claim 16 depends from claim 12.

It is believed that the application is in proper form for examination and such action is respectfully solicited.

Respectfully submitted,

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**VERSION OF AMENDMENT WITH MARKINGS TO SHOW CHANGES MADE**

**IN THE CLAIMS**:

7. (Amended) A side-emission type semiconductor light-emitting device according to [any one of claims 4 to 6] claim 4, wherein said LED chip has a bonding wire extending from a top surface, and said concave portion is formed directly above said LED chip.

13. (Amended) A side-emission type semiconductor light-emitting device according to claim 11 [or 12], wherein a center of said application area is deviated from a center of said substrate to said opposite direction.